

To our customers,

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## Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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# HZM7.5FA

Silicon Epitaxial Planar Zener Diode for Surge Absorb

**RENESAS**

ADE-208-616B (Z)

Rev.2  
Nov. 2002

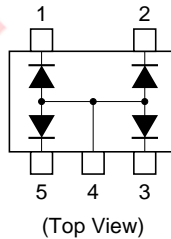
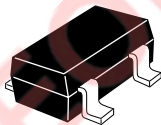
## Features

- HZM7.5FA has four devices, and can absorb surge.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HZM7.5FA	75A	MPAK-5

## Pin Arrangement



1. Cathode
2. Cathode
3. Cathode
4. Anode
5. Cathode

## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: Four device total, See Fig.2.

## Electrical Characteristics \*<sup>1</sup>

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V <sub>z</sub>	7.06	—	7.84	V	I <sub>z</sub> = 5 mA, 40 ms pulse
Reverse current	I <sub>R</sub>	—	—	2	μA	V <sub>R</sub> = 4 V
Capacitance	C	—	—	125	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Dynamic resistance	r <sub>d</sub>	—	—	30	Ω	I <sub>z</sub> = 5 mA
ESD-Capability * <sup>2</sup>	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes: 1. Per one device.

2. Failure criterion ; I<sub>R</sub> > 2 μA at V<sub>R</sub> = 4 V.

Main Characteristic

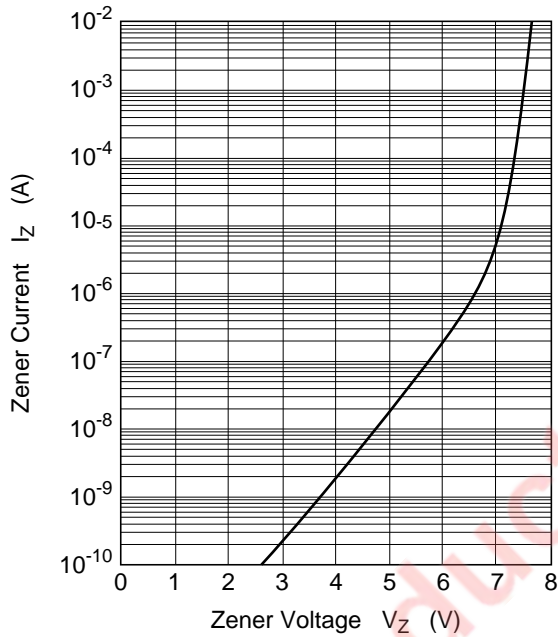


Fig.1 Zener current vs. Zener voltage

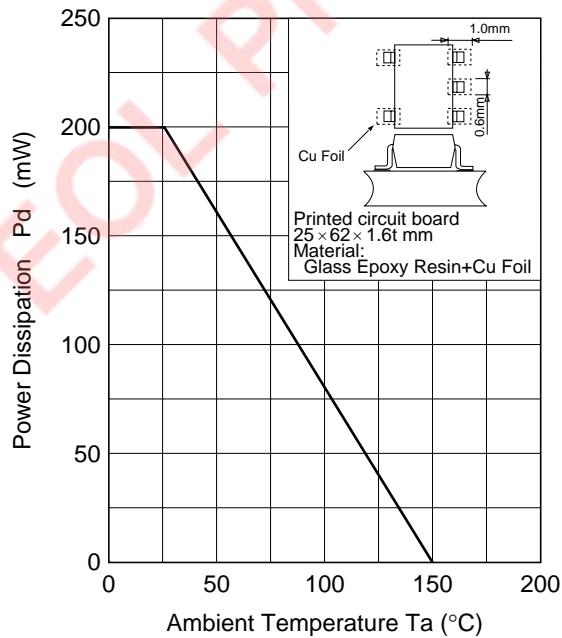


Fig.2 Power Dissipation vs. Ambient Temperature

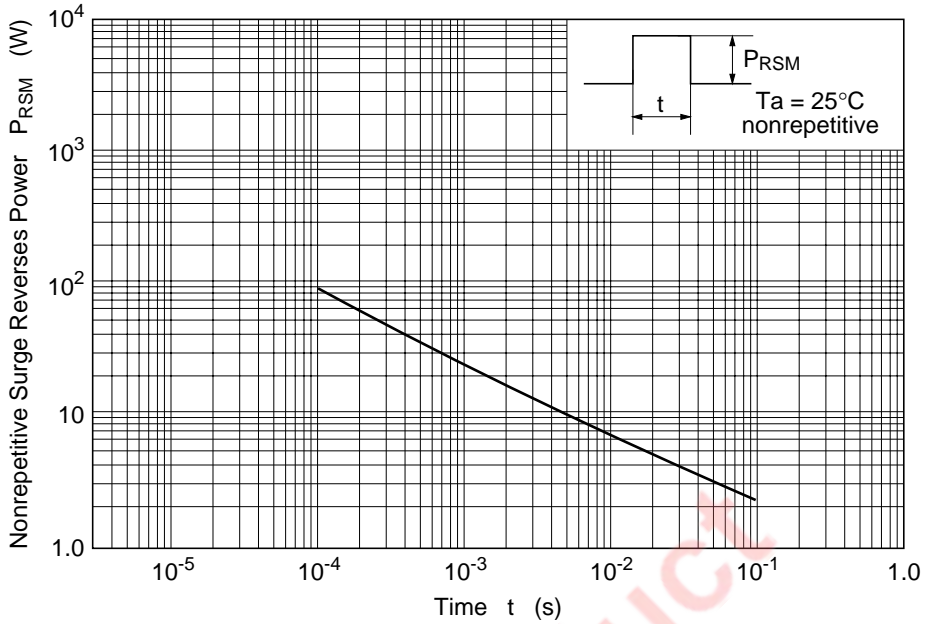


Fig.3 Surge Reverse Power Ratings

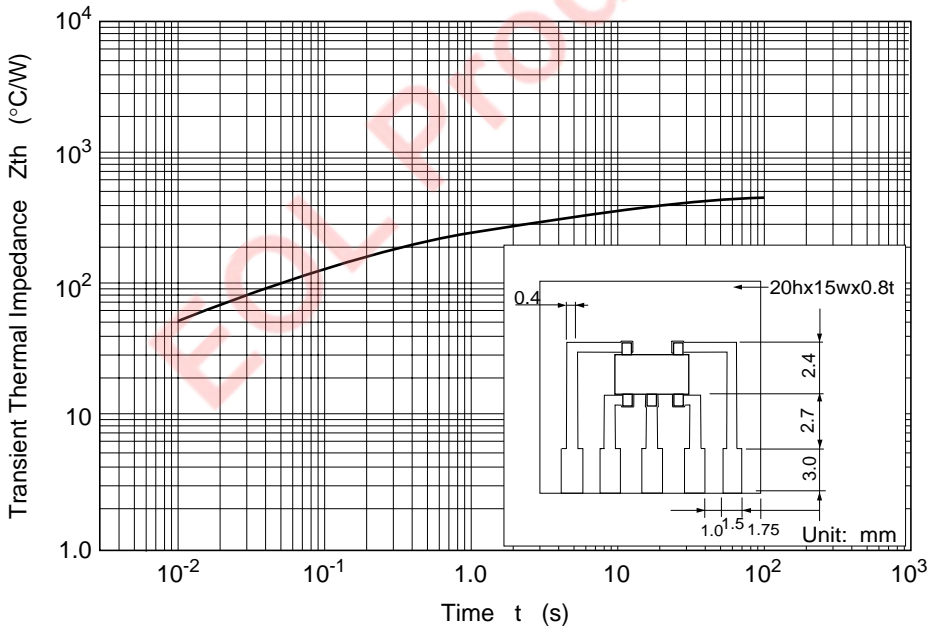
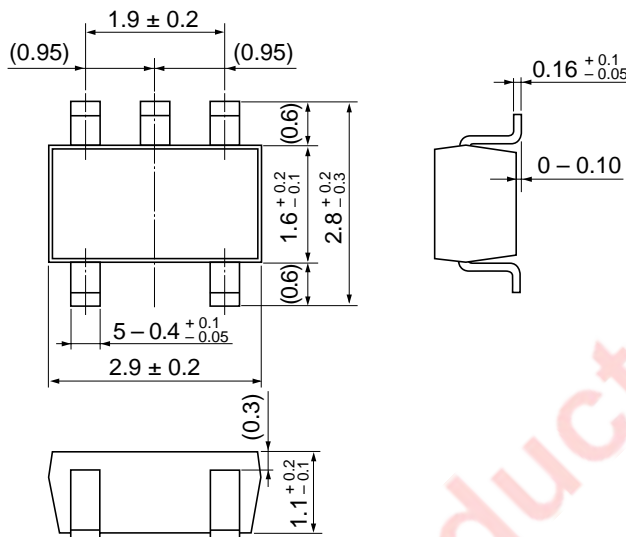


Fig.4 Transient Thermal Impedance



Package Dimensions

As of July, 2002  
Unit: mm



Hitachi Code	MPAK-5
JEDEC	—
JEITA	—
Mass (reference value)	0.013 g

EOL Product

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